



IBM Docket No. FI5920030074US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: **Emanuel I. Cooper et al.**

Serial No.: **10/604,560**

Date: **October 6, 2004**

Filed: **July 30, 2003**

Group Art Unit: **2825**

Title: **INHIBITION OF TIN OXIDE FORMATION
IN LEAD FREE INTERCONNECT
FORMATION**

Examiner: **Calvin Lee**

DeLIO & PETERSON, LLC
121 Whitney Avenue
New Haven, CT 06510-1241

LETTER TO OFFICIAL DRAFTSMAN

Mail Stop **ISSUE FEE**
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Applicants are herewith submitting 2 sheets of Formal Drawings for the approval of the Draftsman. A marked-up copy is enclosed showing the changes.

Please charge the Assignee IBM Corporation Deposit Account No. **09-0458** for any fee related to the acceptance of the attached Formal Drawings. A duplicate copy of this letter is enclosed for that purpose.

Respectfully submitted,

BY:

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